

What is claimed is :

1. In a heat sink (1) molded employing diamond, said heat sink characterized by cemented carbide (2) and diamond powder (3) admixed thereto;

wherein the said diamond powder consists of high-purity diamond particles having a particle size of 0.1 to 100 μm , whereas said cemented carbide consists primarily of WC and, as the rest, at least one metal selected from Co, Ni and Fe and inevitable impurity.

2. The heat sink according to Claim 1, characterized in that the proportion of said diamond powder admixed relative to said cemented carbide is 5 to 90%.

3. An electronic device characterized in that the heat sink as set forth in any of Claims 1 to 2 which is combined in thermal contact.

4. ~~A process for producing a heat sink characterized by a step of subjecting a particulate mixture of diamond, WC, Co, etc. to sintering at a temperature of 1200 to 1500 °C under a pressure of 3 to 6 GPa.~~